

LCM							
NO.	Pin name						
1	VDD	11	NIND2	21	SCL	31	LED+
2	VDD	12	PIND2	22	CSB	32	LED+
3	VDD	13	GND	23	NC	33	NC
4	NC	14	CLKN	24	VGH	34	LED-
5	NINDO	15	CLKP	25	VGL	35	LED-
6	P1ND0	16	GND	26	NC	36	LED-
7	CND	17	NIND3	27	VSP	37	NC
8	N1ND1	18	PIND3	28	VSN	38	NC
9	P1ND1	19	NC	29	NC	39	NC
10	GND	20	SDA	30	LED+	40	NC

- 1. Display size:10.1"TFT
  2. Mewing direction:FULL VIEW
  3. Display mode:Transmissive/Normal Black/Anti-Glare
  4. Operation temperature:-20°C~+70°C

- 5. Storage temperature:-30°C~+80°C 6. Power supply voltage:3.3V 7. Driver IC:EK79202DB 8. Backlight :White(42 LED)/18.6V/140mA
- 9.Brightness:300(TYP)cd/m2
- 10.ROHS must be complied
- 11. The dimension with mark brackets "()" just for reference
  \* Unspecification tolerance are ±0.3mm

Compliance: RohS III (2015/863/EU)

Tolerances:			Date	Name				
			01/25	dr	VDE			
					YDP LCD I 1010 AG LV			
						00 50	07	Page
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						000	<u> </u>	1/25
Modifications	Date	Name						

## **PRODUCT SPECIFICATION**

# 10.1" IPS TFT LCD MODULE MODEL: YDP LCD | 1010 AG LVDS Ver: 1.1

- < >> Preliminary Specification
- < ◆> Finally Specification

CUSTOMER'S APPROVAL					
CUSTOMER:					
SIG	NATURE:	DATE:			

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
TFT	TFT	TFT	TFT
Y. B	S. G. H	周福云	L. L
20240205	20240205	20240205	20240205

## **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2023.12.15	LQ	Initial Release	
1.1	2024.02.05	LL	Modify Backlight Characteristic  Modify Optical Characteristics  Modify Outline Drawing	P5 P6 P25

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## 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

## 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	10.1"	
LCD type	IPS TFT	
Display Mode	Transmissive/ Normally Black	
Resolution	1280 RGB x 800	Pixels
View Direction	FULL VIEWING	Best Image
Module Outline	229.46 (H) x 149.1(V) x 2.8(T) (Note1)	mm
Active Area	216.96 (H) x 135.6(V)	mm
Pixel Size	169.5 (H) x 169.5(V)	um
Pixel Arrangement	RGB Stripe	
Polarizer Surface Treatment	Anti-Glare	
Display Colors	16.7M	
Interface	LVDS interface	
Driver IC	EK79202DB	
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

## 3. Absolute Maximum Ratings

GND=0V, Ta=25°C

ltem	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.5	4.0	V
Storage temperature	Тѕтс	-30	80	°C
Operating temperature	T <sub>OP</sub>	-20	70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

## 4. DC Characteristics

ltem	Symbol	Min.	Тур.	Max.	Unit
	VDD	3.0	3.3	3.6	V
	VGH	17.5	18.0	18.5	V
Supply Voltage/current	VGL	-11.5	-10.5	-10	V
	VSP	4.5	5.0	6	V
	VSN	-6	-5.0	-4.5	V
Differential input high threshold voltage	Rxvth	-	-	0.1	V
Differential input low threshold voltage	RXVTL	-0.1	-	-	V
Input voltage range (singled-end)	R <sub>XVIN</sub>	0.7	-	1.7	V
Differential input voltage	[VID]	0.2	-	0.6	V
Current Consumption All White	I <sub>DD</sub>	-	TBD	-	٧

## 5. Backlight Characteristic

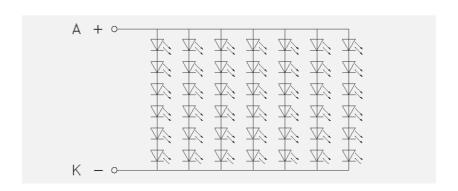
## 5.1. Backlight Characteristic

ltem	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	Ta=25 °C, I <sub>F</sub> =20mA/LED	16.8	18.6	20.4	٧
Forward Current	lF	Ta=25 °C, V <sub>F</sub> =3.1V/LED	-	140	-	mΑ
Power dissipation	Pb		-	2604	1	mW
Uniformity	Avg		-	80	1	%
LED working life(25°C)	- 30,000 -				Hrs	
Drive method	Constant current					
LED Configuration	42 White LEDs(6 LEDs in one string and 7 groups in parallel)					

Note:LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C,60%RH±5%, I<sub>F</sub>=20mA/LED.

## 5.2. Backlighting circuit



## 6. Optical Characteristics

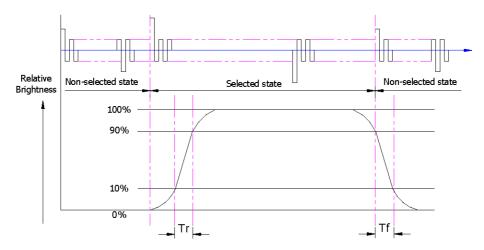
## 6.1. Optical Characteristics

Ta=25°C, VDD=3.3V

	ltem		Symbol	Condition	S	pecification	on	Unit
	iten	ı	Symbol	Condition	Min.	Тур.	Max.	Offic
	Luminan	ce on						
(a)	$TFT(I_f = 20)$	mA/LED)	Lv	Normally viewing	240	300	•	cd/m²
Mode)	Contrast ratio	(See 6.3)	CR	angle	800	1000	-	
On (Transmissive M	Response time (See 6.2)		TR+TF	θx = φy =0°	-	25	35	ms
l iši —		Red	Xr		-	TBD	-	
nsr		Red	Yr		-	TBD	=	
Tra	Chromoticity	1	Xg		ı	TBD	ı	
] u	Chromaticity		Yg		ı	TBD	ı	
	Transmissive (See 6.5)	Blue	Хв		ı	TBD	ı	-
  ligh	(000 0.0)	Dide	Yв		ı	TBD	-	
Backlight		White	Xw		-	TBD	-	
m		VVIIILE	Yw		-	TBD	-	
	Viewing	Horizontal	Өх+		70	80	-	
	Viewing Angle	Tionzontal	Өх-	Center	70	80	-	Deg.
	(See 6.4)	Vertical	φΥ+	CR≥10	70	80	-	Deg.
	(000 0.4)	Vertical	φΥ-		70	80	-	
	NTSC Ratio	(Gamut)			45	50	ı	%

## 6.2. Definition of Response Time

## 6.2.1 Normally Black Type (Negative)



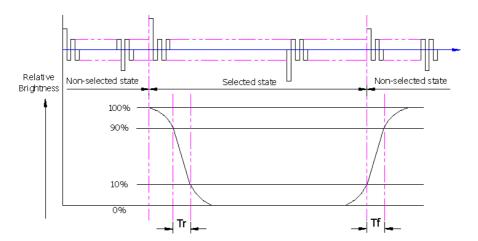
Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to

non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

## 6.2.2 Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

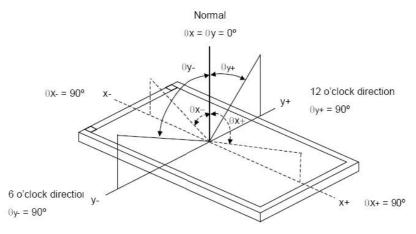
#### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent		
Measuring Point Diameter	3mm//1mm		
Measuring Point Location	Active Area centre point		
Toot nottorn	A: All Pixels white		
Test pattern	B: All Pixel black		
Contrast setting	Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

#### 6.4. Definition of Viewing Angles

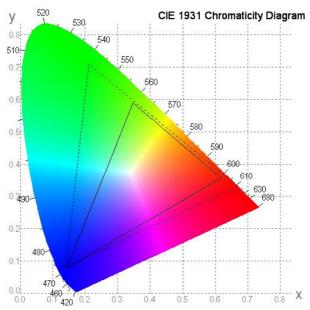


Measuring machine: LCD-5100 or EQUI

## 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

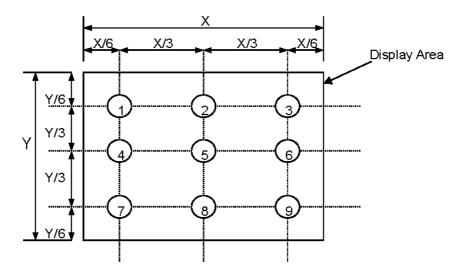


## 6.6. Definition of Surface Luminance, Uniformity and Transmittance

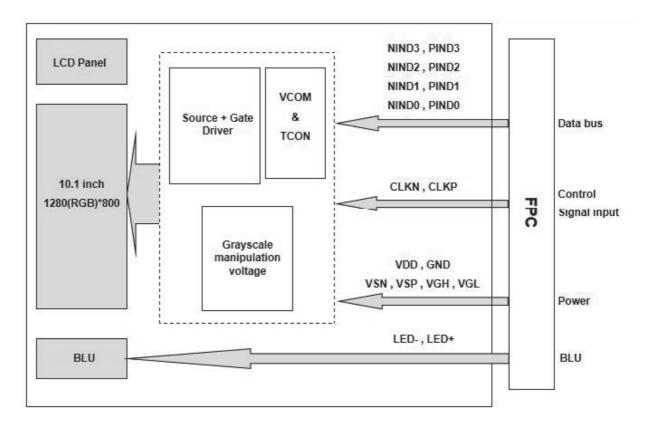
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1 Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2 Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3 Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



## 7. Block Diagram and Power Supply



## 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	VDD	Power Supply Voltage	
2	VDD	Power Supply Voltage	
3	VDD	Power Supply Voltage	
4	NC	No connection	
5	NIND0	LVDS data Input Signal-	
6	PIND0	LVDS data Input Signal+	
7	GND	Ground	
8	NIND1	LVDS data Input Signal-	
9	PIND1	LVDS data Input Signal+	
10	GND	Ground	
11	NIND2	LVDS data Input Signal-	
12	PIND2	LVDS data Input Signal+	
13	GND	Ground	
14	CLKN	LVDS clock Input Signal-	
15	CLKP	LVDS clock Input Signal+	
16	GND	Ground	
17	NIND3	LVDS data Input Signal-	
18	PIND3	LVDS data Input Signal+	
19	NC	No connection	
20	SDA	No connection	
21	SCL	No connection	
22	CSB	No connection	
23	NC	No connection	
24	VGH	Gate On voltage.	
25	VGL	Gate Off voltage.	
26	NC	No connection	
27	VSP	Input voltage from the set-up circuit (4.5V to 6.0V).	
28	VSN	Input voltage from the set-up circuit (-4.5V to -6.0V).	
29	NC	No connection	
30	LED+	LED Driver Power Supply.	
31	LED+	LED Driver Power Supply.	
32	LED+	LED Driver Power Supply.	
33	NC	No connection	
34	LED-	LED Driver Ground.	
35	LED-	LED Driver Ground.	
36	LED-	LED Driver Ground.	
37	NC	No connection	
38	NC	No connection	
39	NC	No connection	
40	NC	No connection	

## 9. AC Electrical Characteristics

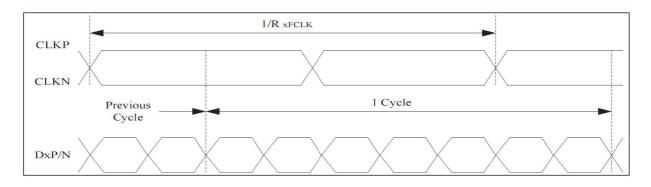
For 1280RGBx800 HV mode

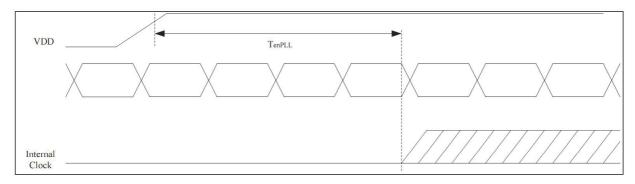
Deremeter		Cumbal	Value			1.1-24
Parameter		Symbol	Min.	Тур.	Max.	Unit
DCLK frequency @Frame rate=	DCLK frequency @Frame rate=60Hz (LVDS)		66.3	72.4	78.9	MHz
HSYNC period time	;	Тн	1380	1440	1500	DCLK
Horizontal display are	еа	Тно		1280		DCLK
	Min.			2		
HSYNC pulse width	Typ.	THPW	-			
	Max.			40		
HSYNC back porch(with pul	HSYNC back porch(with pulse width)		88	88	88	DCLK
HSYNC front porch		THEP	12 72 132		132	DCLK
VSYNC period time	•	Tv	824 838 872		872	Н
Vertical display area	а	TvD		800		Н
	Min.			2		Н
VSYNC pulse width	Typ.	TVPW		28		
	Max.	1 [		20		
VSYNC back porch(with pul	se width)	T <sub>VBP</sub>	23	23	23	Н
VSYNC front porch	í	TVFP	1	15	49	Н

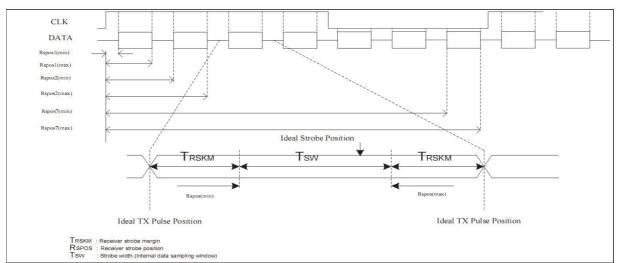
## For 1280RGBx800 DE mode

Daramatar	O. mah al	Value			I I wit
Parameter	Symbol	Min.	Тур.	Max. 78.5 1500 220 872 72	Unit
DCLK frequency @Frame rate=60Hz (LVDS)	FDCLK	68.2	72.4	78.5	MHz
Horizontal display area	T <sub>HD</sub>		1280	÷	DCLK
HSYNC period time	T <sub>H</sub>	1380	1440	1500	DCLK
HSYNC blanking	T <sub>HBP</sub> +T <sub>HFP</sub>	100	160	220	DCLK
Vertical display area	Tvo		800		Н
VSYNC period time	Tv	824	838	872	Н
VSYNC blanking	T <sub>VBP</sub> +T <sub>VFP</sub>	24	38	72	Н

B	0	Spec.			III.		
Parameter	Symbol	Min. Typ.		Max.	Unit	Condition	
Clock frequency	RxFCLK	30	( <b>-</b> 0)	TBD	MHz	Refer to input timing table for each display resolution	
Input data skew margin	Trskm	500	-		ps	VID  = 200mV RxVCM = 1.2V RxFCLK = 81MHz	
Clock high time	TLVCH	5	4/(7* RxFCLK)	070	ns		
Clock low time	TLVCL	5.1	3/(7* RxFCLK)	070	ns		
PLL wake-up time	TenPLL	5.	-	150	us		

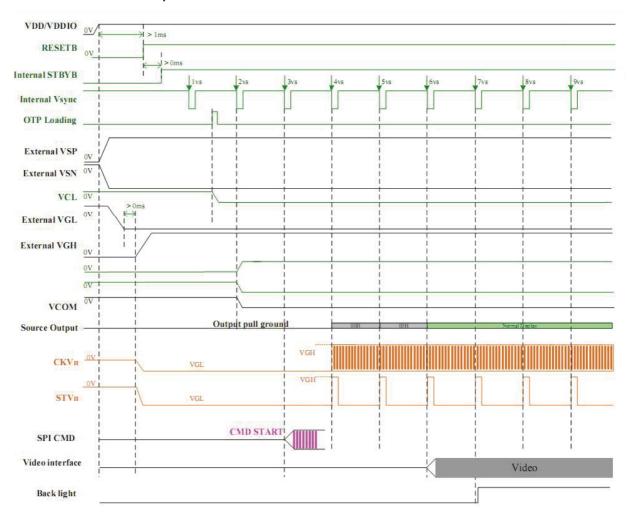






## 10. Power ON/OFF sequence

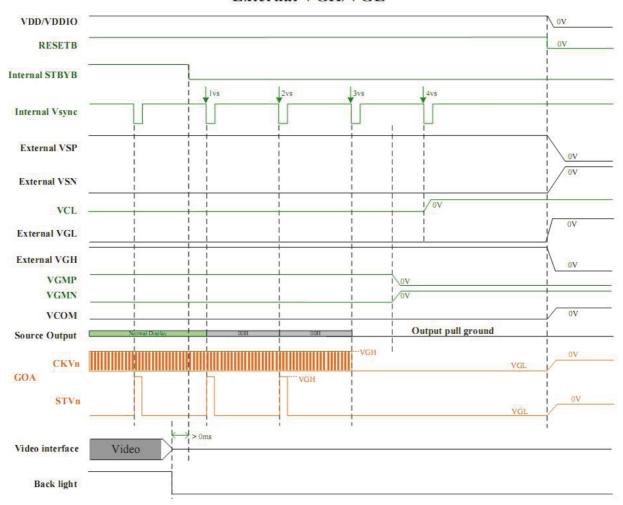
## 10.1. Power ON Sequence



Note:Before Power on process is have to check all power input of external that is GND.

## 10.2.Power OFF Sequence

## External VSP/VSN External VGH/VGL



## 11. Quality Assurance

#### 11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer

### 11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5 Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

## 11.3. Nonconforming Analysis & Disposition

- 11.3.1. Nonconforming analysis:
  - 11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 11.3.1.3. If can not finish the analysis on time, customer will be notified with the progress status.
- 11.3.2. Disposition of nonconforming:
  - 11.3.2.1. Non-conforming product over PPM level will be replaced.
  - 11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

#### 11.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

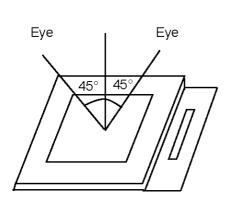
- 11.4.1. There is any discrepancy in standard of quality assurance.
- 11.4.2. Additional requirement to be added in product specification.
- 11.4.3. Any other special problem.

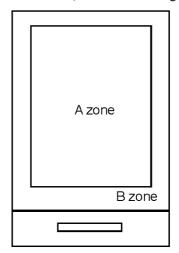
## 11.5. Standard of the Product Visual Inspection

- 11.5.1. Appearance inspection:
  - 11.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,





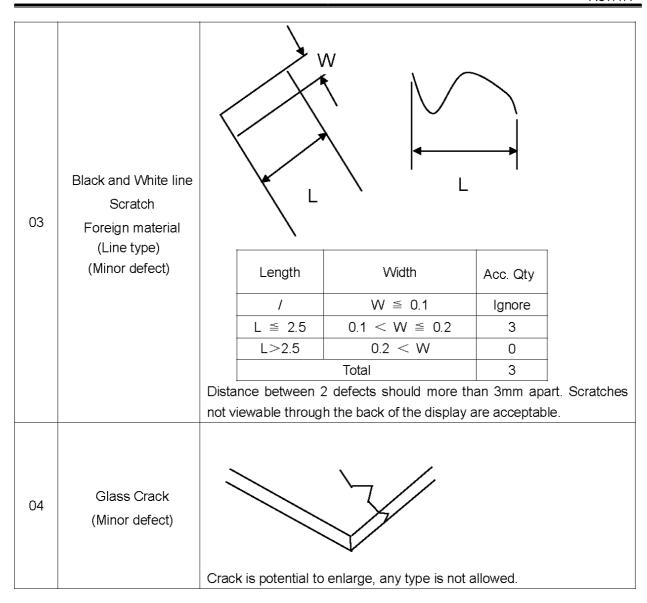
## 11.5.2. Basic principle:

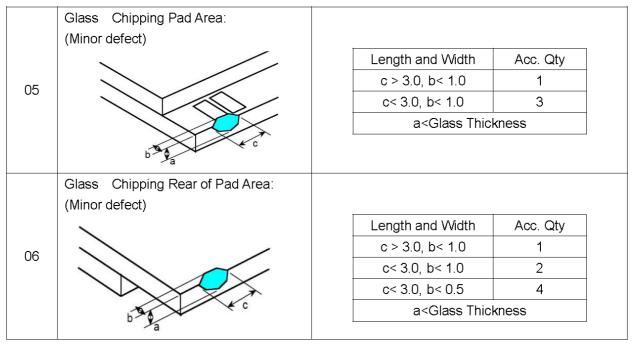
11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

11.5.2.2. New item must be added on time when it is necessary.

## 11.6.Inspection Specification

No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	$\phi$ = (a + b) /2 Distance between 2	Size  φ≤0 0.20<φ 0.50	0.20 I p≤0.50 0<φ	cc. Qty gnore N≤3 0
02	Electrical Defect (Minor defect)	Bright dot  Dark dot  Total dot  Mura	Display Area N≤2 N≤4 N≤4 Not visible throug	Total N≤2 N≤4 N≤4 gh 5% ND filters.	Note1
		Remark:  1. Bright dot cause	d by scratch and fore	ign object accords	to item 1.





	Glass Chipping Except Pad Area: (Minor defect)				
	l` (	Γ	Length and Width	Acc. Qty	
07			c > 3.0, b< 1.0	1	
07			c< 3.0, b< 1.0	2	
	0 3		c< 3.0, b< 0.5	4	
			a <glass td="" thicl<=""><td>kness</td><td></td></glass>	kness	
08	Glass Corner Chipping: (Minor defect)		Length and Width c < 3.0, b< 3.0 a <glass td="" thick<=""><td>Acc. Qty Ignore kness</td><td></td></glass>	Acc. Qty Ignore kness	
09	Glass Burr: (Minor defect)	Glass	Length F < 1.0  burr don't affect assion.	Acc. Qty Ignore	odule
10	FPC Defect: (Minor defect)	(w: circ 10.2 Op	ent, pinhole width a <w <br="">uitry width.) pen circuit is unaccepta o oxidation, contaminat</w>	able.	า.

11	Bubble on Polarizer (Minor defect)	Diameter φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤2 N=0		
12	Dent on Polarizer (Minor defect)	Diameter φ≤0.25 0.25 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤4 None		
13	Bezel	<ul><li>13.1 No rust, distortion on the Bezel.</li><li>13.2 No visible fingerprints, stains or other contamination.</li></ul>			
14	PCB	<ul><li>14.1 No distortion or contamination on PCB terminals.</li><li>14.2 All components on PCB must same as documented on the BOM/component layout.</li><li>14.3 Follow IPC-A-600F.</li></ul>			
15	Soldering	Follow IPC-A-610C standard			
16	Electrical Defect (Major defect)	The below defects must be rejected.  16.1 Missing vertical / horizontal segment,  16.2 Abnormal Display.  16.3 No function or no display.  16.4 Current exceeds product specifications.  16.5 LCD viewing angle defect.  16.6 No Backlight.  16.7 Dark Backlight.  16.8 Touch Panel no function.			

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

## 11.7. Classification of Defects

- 11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2. Two minor defects are equal to one major in lot sampling inspection.

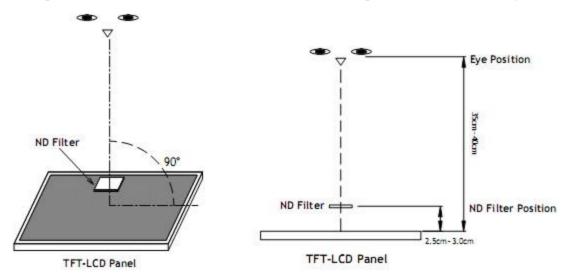
## 11.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 11.9. Packing

- 11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2. Modules inside package box should have compliant mark.
- 11.9.3. All direct package materials shall offer ESD protection.

Note1:Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixelarea.



Bright dot:The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm ±50mm.

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

## 12. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	<b>70</b> ℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
	Lieothoai Static Discharge	Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times		-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

## 13. Precautions and Warranty

#### 13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

#### 13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

#### 13.3. Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

## 13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

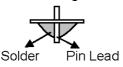
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



Recommended



## 13.4.2. Pins of EL

13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

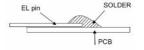
Typical Soldering Time: ≤2s

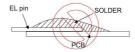
Minimum solder distance from EL lamp (body):2.0mm

13.4.2.4. No horizontal press on the EL leads during soldering.

13.4.2.5. 180° bend EL leads three times is not allowed.

#### 13.4.2.6. Solder Wetting





Recommended

Not Recommended

13.4.2.7. The type of the solder iron:





Recommended

Not Recommended

13.4.2.8. Solder Pad



## 13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

## 13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 13.7.Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

## 14. Packaging

TBD